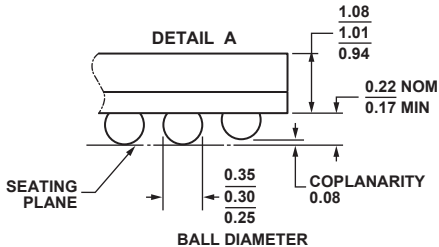
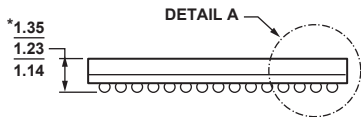
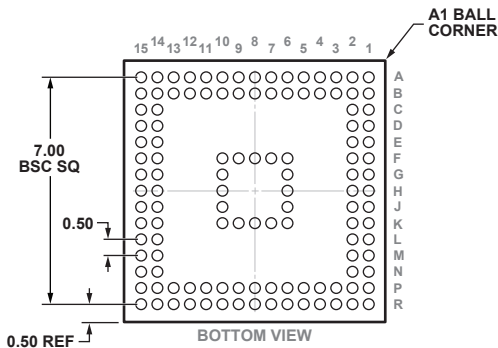
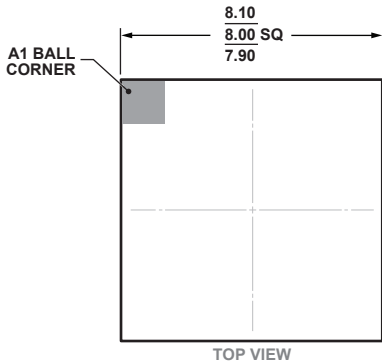


**120-Ball Chip Scale Package Ball Grid Array [CSP\_BGA]  
(BC-120-3)**

Dimensions shown in millimeters



\*COMPLIANT TO JEDEC STANDARDS MO-275-CCCE-1 WITH EXCEPTION TO PACKAGE HEIGHT.